PRELIMINARY

SuperQ™ 200-V N-Channel Power MOSFET

FEATURES

- Wide SOA and current capability
- Robustness under fault conditions
- Optimized linear mode operation
- Efficiency under normal operation (low R_{DS(on)}, Q_{SW}, E_{OSS})

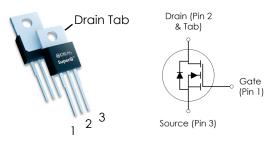
APPLICATIONS

- Motor control
- Boost converters and SMPS control FETs
- Secondary side synchronous rectifier

DESCRIPTION

Engineered for high-efficiency motor drives, this 200V SuperQ MOSFET delivers ultra-low conduction and switching losses in a robust TO-220 package. Featuring best-in-class $R_{DS(on)}$ and Q_{SW} , it minimizes heat dissipation at both full and partial loads.

PRODUCT SUMMARY



TO-220

Parameter T _A = 25°C	Value	Unit
V _{DS}	200	V
R _{DS} (on),max	6.3	mΩ
ID	141	Α
Q _G	116	nC
Qsw	12.4	nC
Eoss	4.2	μJ







ORDERING INFORMATION					
Part Number	Package	Marking	Packaging		
iS20M6R3S1P	TO-220	iS20M6R3S1P	50pc Tube		

BSOLUTE MAXIMUM RATINGS						
SYMBOL	PARAMETER (T _A = 25°C unless otherwise specified)	VALUE	UNIT			
V_{GS}	Gate-to-source voltage	<u>+</u> 20	V			
	Continuous drain current (silicon limited), $T_C = 25^{\circ}C$	141	А			
l _D	Continuous drain current (silicon limited), T _C = 100°C	100				
I _{DM}	Pulsed drain current	561	Α			
P _D	Power dissipation, $T_C = 25^{\circ}C$	300	W			
T _J , T _{stg}	Operating junction, storage temperature	-55 to 175	°C			
E _{AS}	Avalanche energy, single pulse I_D = 84A, R_{GS} = 25 Ω	350	mJ			

THERMAL CHARACTERISTICS

SYMBOL	DADAMETED (7 office to the control of the control o	VALUE			LINUT
STMBOL	PARAMETER (T _A = 25°C unless otherwise specified)		TYP	MAX	UNIT
R _{0JC}	Junction-to-case thermal resistance - TO-220	-	-	0.5	°C/W
R _{OJA}	Junction-to-ambient thermal resistance (1)	-	-	50	°C/W

(1) 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.



PRELIMINARY

iS20M6R3S1P

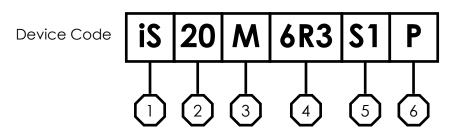
SYMBOL	PARAMETER		VALUE			
		TEST CONDITIONS	MIN	TYP	MAX	UNIT
STATIC CI	HARACTERISTICS					
BV _{DSS}	Drain-to-source voltage	$V_{GS} = 0V$, $I_D = 1mA$	200	-	-	٧
	Drain-to-source leakage current	$V_{GS} = 0V$, $V_{DS} = 160V$, $T_J = 25$ °C	-	0.1	1	μΑ
I _{DSS}		$V_{GS} = 0V$, $V_{DS} = 160V$, $T_J = 125$ °C (2)	-	-	100	
lgss	Gate-to-source leakage current	$V_{DS} = 0V$, $V_{GS} = 20V$	-	30	100	nA
V _{GS(th)}	Gate-to-source threshold voltage	$V_{DS} = V_{GS}$, $I_D = 300 \mu A$	2.8	3.5	4.2	V
R _{DS(on)}	Drain-to-source on-resistance	$V_{GS} = 10V, I_D = 30A$	-	5.5	6.3	mΩ
G fs	Transconductance	V _{DS} = 10V, I _D = 30A	68	136	-	S
DYNAMIC	CHARACTERISTICS					
Ciss	Input capacitance (2)		-	7,607	10,042	
Crss	Reverse transfer capacitance (2)	$V_{GS} = 0V$, $V_{DS} = 100V$, $f = 100kHz$	-	47	61	pF
Coss	Output capacitance (2)		-	289	376	
C _{o(er)}	Effective output capacitance	$V_{DS} = 0$ to 100V, $V_{GS} = 0$ V	-	838	-	
R _G	Series gate resistance	f = 1MHz	-	1.2	1.8	Ω
t _{d(on)}	Turn-on delay time		-	TBD	-	
t _r	Rise time	$V_{DS} = 100V$, $V_{GS} = 10V$, $I_{DS} = 30A$, $R_{G,EXT} = 0 \Omega$	-	TBD	-	
t _{d(off)}	Turn-off delay time		-	TBD	-	ns ns
† _f	Fall time		-	TBD	-	
GATE CH	ARGE CHARACTERISTICS					
Qgs	Gate to source charge		-	60	-	
Qg	Gate charge total (2)		-	116	152	
Qsw	Switching charge (3)	$V_{DS} = 100V, I_{D} = 30A,$	-	12.4	-	nC
Q _{gd}	Gate to drain charge (2)	V _{GS} = 0 to 10V	-	22	32	
Qg(th)	Gate charge at threshold		-	27	-	
V _{plateau}	Gate plateau voltage		-	5.5	-	٧
Qoss	Output charge (2)		-	356	458	nC
E _{oss}	Capacitive stored energy	$V_{DS} = 0$ to 100V, $V_{GS} = 0$ V	-	4.2	-	μJ
DIODE CH	IARACTERISTICS					
V _{SD}	Diode forward voltage	I _{SD} = 30A, V _{GS} = 0V	-	1.1	1.3	V
Qrr	Reverse recovery charge	V _{DS} = 100V, I _F = 30A,	-	1.1	-	μC
t _{rr}	Reverse recovery time	di/dt = 100A/µs	-	244	-	ns

⁽²⁾ Defined by design. Not subject to production test.

⁽³⁾ Qsw should be used for switching loss calculations. See Qsw application note on www.idealsemi.com



DEVICE DECODER RING

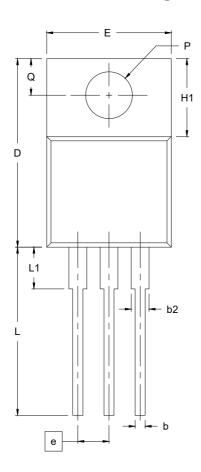


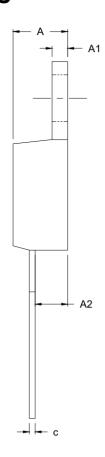
- (1) iDEAL Semiconductor product
- Voltage rating divided by 10 (200V)
- M = N-Channel MOSFET, Standard Threshold
- Maximum drain-to-source resistance
- 5 SuperQ™ Generation
- **(**6**) -** P = TO-220





TO-220 Package Drawing





SYMBOL	MIN	MAX		
Α	4.19	4.82		
A1	1.14	1.40		
A2	2.38	2.92		
b	0.63	1.01		
b2	1.13	1.78		
С	0.31	0.64		
D	14.22	16.51		
E	9.66	10.66		
е	2.54 BSC			
H1	5.85	6.85		
L	12.70	14.73		
L1	2.39	4.42		
Р	3.54	4.08		
Q	2.54	3.42		
Notes				

- All linear dimensions in millimeters
 Dimensions D and E do not include mold flash or protrusions





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